

PCN Number:	20160117003	PCN Date:	1/18/2016
Title:	Datasheet for DAC3482		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



DAC3482

SLAS748F – MARCH 2011 – REVISED AUGUST 2015

Changes from Revision E (February 2013) to Revision F

Page

• Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
• Added NFBGA package to Description	1
• Added additional operation requirement for SLEEP pin if SLEEP pin is set to logic HIGH before and during device power up and initialization - RKD package.....	8
• Added additional circuit configuration for unused terminals.....	11
• Changed DAC3484 to DAC3482 in SDENB description	11
• Added additional operation requirement for SLEEP pin if SLEEP pin is set to logic HIGH before and during device power up and initialization - ZAY package.....	11
• Changed parameter name Single-Ended Swing Level to Single-Ended Input Level to better reflect the specification for minimum recommended single-ended voltage level.....	15
• Added DACCLK and OSTR minimum voltage note to Electrical Characteristics – Digital Specifications	15
• Added text and application report link to Input FIFO section	31
• Added reference to LMK0480x family in Input FIFO section.....	32
• Added pin number per package for LPF pin in PLL Mode section.....	38
• Changed figure and table references in FIR Filters section.....	39
• Changed first paragraph in Complex Signal Mixer section	42
• Deleted redundant text from Related Documentation section.....	50
• Changed point to pointer in DAC3482 Alarm Monitoring section.....	50
• Changed point to pointer in DAC3482 Alarm Monitoring section.....	50
• Added note to Figure 80	52
• Added V_{COM} values to Table 9	53
• Added Unused LVDS Port Termination section	53

- Added clarification on timing requirement acronyms to [Multi-Device Synchronization: PLL Enabled with Dual Sync Sources Mode](#) 59
- Deleted or in [Power-Up Sequence](#) description 62
- Changed P = 3 to P = 4 in [PLL Configuration](#) to reflect the correct example start-up routine configuration 62
- Added pin description for both packages 69
- Changed Config7, bit 3 naming typo 71
- Changed config10 to config11 and 0x0A to 0x0B in register config11 72
- Changed QMC offset registers to QMC correction registers in config16 function 73
- Changed Qfine to fine in config18 function 73
- Added reference in config26 function 75
- Added additional operation requirement for SLEEP pin if SLEEP pin is set to logic HIGH before and during device power up and initialization in config27 function 76
- Changed 1.2VDIG to DIGVDD in config27 function 76
- Added pin description for both packages to register config35 description 79
- Added reference to Digital Input Timing Specifications in register config36 description 79

The datasheet number will be changing.

Device Family	Change From:	Change To:
DAC3482	SLAS748E	SLAS748F

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DAC3482>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DAC3482IRKD25	DAC3482IRKDR	DAC3482IRKDT	DAC3482IZAY	DAC3482IZAYR
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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